

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listing of claims in the application.

1. (Original) A method for low dark current imaging, comprising:  
forming a first well of a first polarity type;  
forming a first oxide layer on the surface of the first well such that the first oxide layer comprises an opening through which a portion of the first well is exposed; and

forming a diode electrode structure of a second polarity type that is opposite the first polarity type wherein the diode electrode structure is formed within an area that is within the exposed portion of the first well such that an intervening portion of the exposed portion of the first well exists between the diode electrode structure and the first oxide layer.

2. (Original) The method of claim 1, wherein the diode electrode structure is formed using an arsenic implant process.

3. (Original) The method of claim 1, wherein the intervening portion of the first well is formed as a continuous area surrounding the diode electrode structure.

4. (Original) The method of claim 1, wherein the diode electrode structure is formed such that a substantial portion of a depletion region that results when a bias voltage is applied to the diode electrode structure does not extend to the first oxide layer.

5. (Original) The method of claim 1, wherein the first well is formed on an epitaxial layer.

6. (Original) The method of claim 1, wherein the oxide layer is formed using a local oxidation of silicon process.

7. (Original) The method of claim 1, wherein the oxide layer is formed using a shallow trench isolation process.

8-18. (Cancelled)